

ABSTRACT

RESIN COMPOSITION FOR SOLDERING, RESIN FLUX CORED SOLDER, FLUX COATED SOLDER, AND LIQUID FLUX

Provided are a resin composition for soldering with not only improved wetting and spreading properties and but also excellent reliability and processability, a resin flux cored solder and a flux coated solder using this resin composition for soldering, and a liquid flux.

The resin composition for soldering includes 1 wt% or more and 40 wt% or less of: any of a dimer acid which is a reaction product of oleic acid and linoleic acid, a trimer acid which is a reaction product of oleic acid and linoleic acid, a hydrogenated dimer acid obtained by adding hydrogen to a dimer acid which is a reaction product of oleic acid and linoleic acid, or a hydrogenated trimer acid obtained by adding hydrogen to a trimer acid which is a reaction product of oleic acid and linoleic acid; or a total of two or more of a dimer acid which is a reaction product of oleic acid and linoleic acid, a trimer acid which is a reaction product of oleic acid and linoleic acid, a hydrogenated dimer acid obtained by adding hydrogen to a dimer acid which is a reaction product of oleic acid and linoleic acid, and a hydrogenated trimer acid obtained by adding hydrogen to a trimer acid which is a reaction product of oleic acid and linoleic acid, and 30 wt% or more and 99 wt% or less of a rosin.

[No Suitable Figure]